

# **ARF465A(G)**

Common Source



# RF POWER MOSFETs N-CHANNEL ENHANCEMENT MODE

300V 150W

The ARF465A and 465B comprise a symmetric pair of common source RF power transistors designed for push-pull scientific, commercial, medical and industrial RF power amplifier applications up to 60 MHz.

Specified 300 Volt, 40.68 MHz Characteristics:

**Output Power = 150 Watts.** 

Gain = 13dB (Class C)

Efficiency = 75%

- Low Cost Common Source RF Package.
- Low Vth thermal coefficient.
- Low Thermal Resistance.
- Optimized SOA for Superior Ruggedness.

#### **MAXIMUM RATINGS**

All Ratings:  $T_C = 25$ °C unless otherwise specified.

Symbol	Parameter	ARF465A/B(G)	UNIT	
V <sub>DSS</sub>	Drain-Source Voltage	1200	Volts	
$V_{\mathrm{DGO}}$	Drain-Gate Voltage	1200	VOILS	
I <sub>D</sub>	Continuous Drain Current @ T <sub>C</sub> = 25°C	6	Amps	
V <sub>GS</sub>	Gate-Source Voltage	±30	Volts	
P <sub>D</sub>	Total Power Dissipation @ T <sub>C</sub> = 25°C	250	Watts	
$R_{\theta JC}$	Junction to Case	0.50	°C/W	
$T_J, T_STG$	Operating and Storage Junction Temperature Range	-55 to 150	°C	
T <sub>L</sub>	Lead Temperature: 0.063" from Case for 10 Sec.	300		

#### STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	МАХ	UNIT
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage ( $V_{GS} = 0V$ , $I_D = 250 \mu A$ )	1200			Volts
V <sub>DS</sub> (ON)	On State Drain Voltage $^{\textcircled{1}}$ (I <sub>D</sub> (ON) = 3A, V <sub>GS</sub> = 10V)			8	VOILS
	Zero Gate Voltage Drain Current (V <sub>DS</sub> = V <sub>DSS</sub> , V <sub>GS</sub> = 0V)			25	μA
DSS	Zero Gate Voltage Drain Current ( $V_{DS} = 0.8 V_{DSS}$ , $V_{GS} = 0V$ , $T_{C} = 125$ °C)			250	μΛ
I <sub>GSS</sub>	Gate-Source Leakage Current $(V_{GS} = \pm 30V, V_{DS} = 0V)$			±100	nA
9 <sub>fs</sub>	Forward Transconductance $(V_{DS} = 25V, I_{D} = 3A)$	3	4		mhos
V <sub>GS</sub> (TH)	Gate Threshold Voltage $(V_{DS} = V_{GS}, I_{D} = 50 \text{mA})$	3		5	Volts

CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

#### **DYNAMIC CHARACTERISTICS**

## ARF465A/B(G)

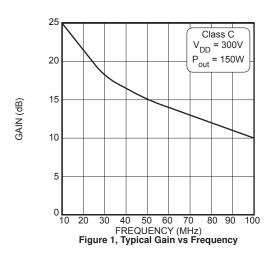
Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V		1200	1500	
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 200V		80	100	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	f = 1 MHz		30	50	
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>GS</sub> = 15V		7	15	
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = 0.5V		5	10	ns
t <sub>d(off)</sub>	Turn-off Delay Time	I <sub>D</sub> = I <sub>D[Cont.]</sub> @ 25°C		21	34	1.5
t <sub>f</sub>	Fall Time	R <sub>G</sub> = 1.6W		12	25	

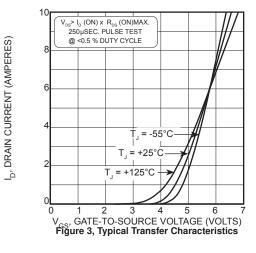
### **FUNCTIONAL CHARACTERISTICS**

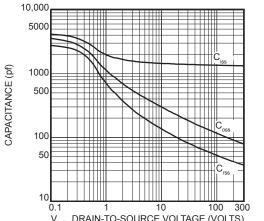
Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
G <sub>PS</sub>	Common Source Amplifier Power Gain	f = 40.68 MHz	13	15		dB
η	Drain Efficiency	$V_{GS} = 0V$ $V_{DD} = 300V$	70	75		%
Ψ	Electrical Ruggedness VSWR 6:1	P <sub>out</sub> = 150W No Degradation in Output		Power		

 $<sup>^{\</sup>bigodot}$  Pulse Test: Pulse width < 380  $\mu\text{S},$  Duty Cycle < 2%

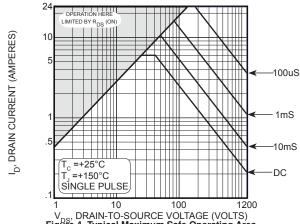
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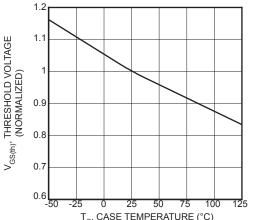




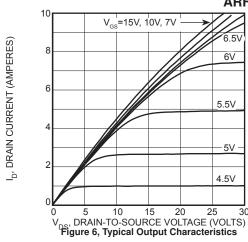
V<sub>D</sub>: DRAIN-TO-SOURCE VOLTAGE (VOLTS)
Figure 2, Drain-to-Source Voltage

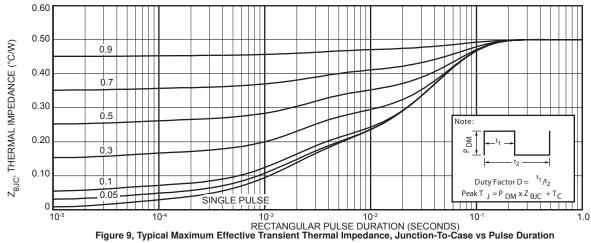


V<sub>DS</sub>, DRAIN-TO-SOURCE VOLTAGE (VOLTS)
Figure 4, Typical Maximum Safe Operating Area









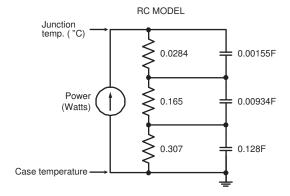


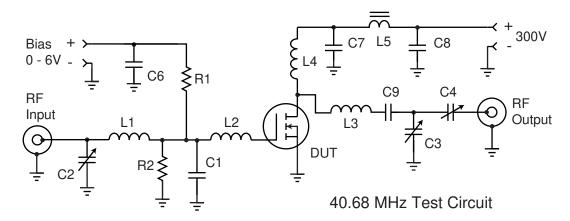
Figure 9a, TRANSIENT THERMAL IMPEDANCE MODEL

Table 1 - Typical Class AB Large Signal input - Output Impedance

Freq. (MHz)	$Z_{in}(\Omega)$	$Z_{OL}(\Omega)$
2.0	21.4 - j 8.7	206 - j 45
13.5	2.6 - j 7.3	68 - j 99
27	.54 - j 2.9	22 - j 64
40	.22 - j .69	10.5 - j 44
65	.31 + j 1.65	4.4 - j 27

 $I_{DQ} = 100 \text{mA}$ 

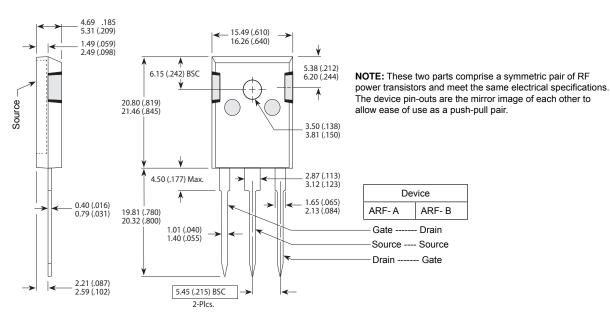
 $Z_{in}$  - Gate shunted with 25 $\Omega$  I<sub>DQ</sub> =  $Z_{OL}$  - Conjugate of optimum load for 150 Watts output at  $V_{dd}$  = 300V



C1 - 1000pF 100V chip ATC 700B C2-C5 - Arco 463 Mica trimmer C6-C8 - .01  $\mu$ F 500V ceramic chip C9 - 2200 pF COG 500 V chip L1 - 4t #20 AWG .25"ID .3"L ~110 nH L2 - 2t #20 AWG .25"ID .3"L ~ 25 nH

L3-- 4t #16 AWG .4" ID .5"L ~290 nH L4 -- 25t #24 AWG .35"ID ~2uH L5-- VK200-4B ferrite choke 3uH R1-R2 -- 51 Ohm 0.5W Carbon DUT = ARF465A/B

### **TO-247 Package Outline**



Dimensions in Millimeters and (Inches)

# **HAZARDOUS MATERIAL WARNING:**

The ceramic portion of the device between leads and mounting flange is beryllium oxide. Beryllium oxide dust is highly toxic when inhaled. Care must be taken during handling and mounting to avoid damage to this area. These devices must never be thrown away with general industrial or domestic waste.

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